

ABSTRACT OF THE DISCLOSURE

An auxiliary lead 6 is arranged so as to support a first semiconductor chip 1 at a corner of a first face of 5 the first semiconductor chip 1 and extend toward an outside of the first semiconductor chip 1, thereby providing a multi-chip package in which a wire does not pass over the auxiliary lead at time of wire bonding so that the auxiliary lead and the wire may not short-circuit with each 10 other.